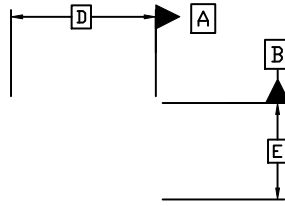


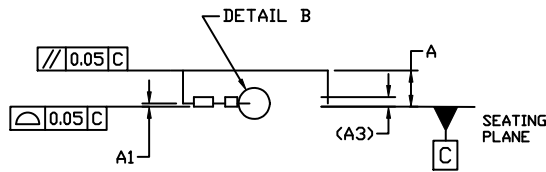
CASE 510BM
ISSUE C

DATE 09 DEC 2019



NOTES:

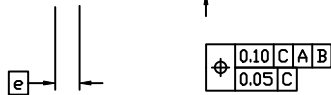
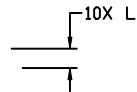
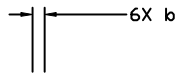
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b AND b1 APPLY TO THE PLATED TERMINALS AND ARE MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.



OPTION

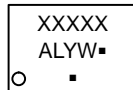


DETAIL A
OPTIONAL CONSTRUCTIONS



RECOMMENDED
MOUNTING FOOTPRINT

DIM	MI	
	MIN.	NOM.
A	0.70	0.80
A1	0.00	0.05
b	0.20	0.30
D	3.00	
E	J	



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.